



Material Content Data Sheet



Sales Product Name	TLE7234EM			Issued	28. August 2013			
MA#	MA000982088							
Package	PG-SSOP-24-4			Weight*	150.84 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.306	2.85	2.85	28546	28546
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8917	
wire	non noble metal	copper	7440-50-8	54.617	36.21	37.15	362087	371561
	noble metal	gold	7440-57-5	0.478	0.32	0.32	3167	3167
	encapsulation	organic material	carbon black	1333-86-4	0.171	0.11		1136
encapsulation	plastics	epoxy resin	-	7.881	5.22		52247	
	inorganic material	silicondioxide	60676-86-0	77.609	51.46	56.79	514517	567900
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19298	19298
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.301	0.20		1994	
	noble metal	silver	7440-22-4	0.902	0.60	0.80	5981	7975
*deviation	< 10%			Sum in total:		100,00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com